

01-22-2004



102651204

Docket No.: NEC 03P198

HEET

U.S. DEPARTMENT OF COMMERCE
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To the Honorable Director of the United States Patent and Trademark Office: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):
Makoto OKADA

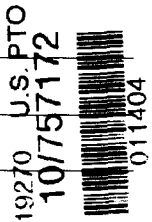
Additional names(s) of conveying party(ies) Yes No

1-14-04

2. Name and address of receiving party(ies):
Name: **NEC Electronics Corporation**
Address: **1753 Shimonumabe**
Nakahara-ku, Kawasaki

City: **Kanagawa** State/Prov.: _____
Country: **JAPAN** ZIP: **211-8668**

Additional name(s) & address(es) Yes No



3. Nature of conveyance:
 Assignment Merger
 Security Agreement Change of Name
 Other _____

Execution Date: **January 9, 2004**

4. Application number(s) or patent numbers(s):
If this document is being filed together with a new application, the execution date of the application is: **January 9, 2004**

Patent Application No. **2004 STEURELL 00000014 10757172**
Filing date **1-14-04**
Additional numbers **40.00 BP**

B. Patent No.(s)

 Yes No **10757172**

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: **Norman P. Soloway**
Registration No. **24,315**
Address: **HAYES SOLOWAY P.C.**
130 W. Cushing Street

City: **Tucson** State/Prov.: **Arizona**
Country: **U.S.A.** ZIP: **85701**

6. Total number of applications and patents involved: **1**

7. Total fee (37 CFR 3.41):.....\$ **40.00**
 Enclosed - Any excess or insufficiency should be credited or debited to deposit account
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8. Deposit account number:
08-1391

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9. Statement and signature.
To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Norman P. Soloway **January 14, 2004**
Name of Person Signing Signature Date

Total number of pages including cover sheet, attachments, and document: **3**

ASSIGNMENT

FOREIGN - IN THE UNITED STATES OF AMERICA

I/we, Makoto OKADA

of Kanagawa, Japan

having invented certain inventions and improvements in MANUFACTURING OF A SEMICONDUCTOR DEVICE WITH A REDUCED CAPACITIVE BETWEEN WIRING

and having executed an application for Letters Patent of the United States of America describing the same and based thereon on

January 9, 2004, for good and valuable consideration, the receipt of which is hereby acknowledged, from NEC Electronics

Corporation a Japanese corporation having its principal place of business at 1753 Shimonumabe, Nakahara-ku, Kawasaki, Kanagawa 211-8668, Japan (hereinafter

called the Assignee), do hereby sell, assign and transfer unto the Assignee, its successors, and assigns our entire rights, title, and interest, in and to said invention in the United States of America, including all rights, title and interest in the above-mentioned application and any divisional, continuing or reissue application or applications, and any patent which may be issued on the said invention in the United States of America.

And for the same consideration, I/we do hereby agree that I/we will upon request execute any instrument which the Assignee may desire to carry this Assignment into effect and perfect the title transferred hereby or prosecute the above-mentioned application.

And I/we do hereby authorize the Commissioner of Patents and Trademarks of the United States of America to issue Letters Patent on the said application to the Assignee.

And I/we do hereby jointly and severally covenant for ourselves and for our legal representatives that I/we have granted no right or license to make, use, or sell said inventions to anyone except the Assignee, that prior to the execution of this deed our rights, title, and interest in and to said inventions or any of them or any part thereof has not been otherwise encumbered by us, and that I/we have not executed and will not execute any instrument in conflict herewith.

IN WITNESS WHEREOF, I/we have hereunto set our hands and seals on the day and year hereinafter noted.

Sole or First

Inventor's signature *Makoto Okada*  Date January 9, 2004
Full name (typed or printed) Makoto OKADA

Witness: *Nitashi Uken*
Date: January 9, 2004

Witness: *[Signature]*
Date: January 9, 2004

Second Inventor's
signature _____ Date _____
Full name (typed or printed) _____

Witness: _____ Witness: _____
Date: _____ Date: _____

Third Inventor's
signature _____ Date _____
Full name (typed or printed) _____

Witness: _____ Witness: _____
Date: _____ Date: _____